L Number	Hits	Search Text	DB	Time stamp
1	33	dummy near leads with (provid$3 or increas$3)	USPAT	2004/04/15 16:14
2	33	Chip with thickness with "50" near microns	USPAT	2004/04/15 16:18
3	35	Chip with thick$4 with "50" near microns	USPAT	2004/04/15 16:22
4	159	Chip with ("50" near microns or "50.mu.m")	USPAT	2004/04/15 16:42
5	574	Chip with thick$4 with (microns or "50.mu.m")	USPAT	2004/04/15 16:43
6	512	(Chip with thick$4 with (microns or "50.mu.m")) not (Chip with ("50" near microns or "50.mu.m"))	USPAT	2004/04/15 16:44
7	1714025	Chip near$5 thick$4 near$5 (microns or "50.mu.m")	USPAT	2004/04/15 17:17
8	314	((Chip with thick$4 with (microns or "50.mu.m")) not (Chip with ("50" near microns or "50.mu.m"))) and lead	USPAT	2004/04/15 16:44
9	1279	Chip with thick$4 with (provid$3 or increas$3)	USPAT	2004/04/15 17:18
11	2	Thin near Chip with thick$4 with (provid$3)	USPAT	2004/04/15 17:18
10	375	Chip with thick$4 with (provid$3)	USPAT	2004/04/15 17:20
12	17	Chip with thick$4 with (benefit)	USPAT	2004/04/15 17:24
13	12	Chip with thickness with (benefit)	USPAT	2004/04/15 17:28
14	10	reducing with Chip with thickness with (providing)	USPAT	2004/04/15 17:29
20	82	(chip or die or semiconductor or IC) and Dummy near lead	JPO	2004/04/15 18:17
—	5773	(semiconductor or die or chip or IC) and (island or dummy) with (electrode or lead or wir$3 or pad)	USPAT	2004/04/12 22:30
—	1353	(semiconductor or die or chip or IC) and (island or dummy) near (electrode or lead or wir$3 or pad)	USPAT	2004/04/12 22:41
—	36	((semiconductor or die or chip or IC) and (island or dummy) near (electrode or lead or wir$3 or pad)) and window with (carrier or substrate or board)	USPAT	2004/04/12 22:41
—	225	((semiconductor or die or chip or IC) and (island or dummy) with (electrode or lead or wir$3 or pad)) and window with (carrier or substrate or board)	USPAT	2004/04/12 22:27
—	3142	(semiconductor or die or chip or IC) and (island or dummy) with (lead or wir$3 or pad)	USPAT	2004/04/12 22:30
—	374	((semiconductor or die or chip or IC) and (island or dummy) with (lead or wir$3 or pad)) and window	USPAT	2004/04/12 22:30
—	28764	(semiconductor or die or chip or IC) and (island or dummy)	USPAT	2004/04/12 23:09
—	909	((semiconductor or die or chip or IC) and (island or dummy)) and window with (carrier or substrate or board)	USPAT	2004/04/12 22:51
—	297	((semiconductor or die or chip or IC) and (island or dummy)) and 257/666	USPAT	2004/04/12 22:51
—	12464	(semiconductor or die or chip or IC) and (dummy)	USPAT	2004/04/12 23:09
—	156	(semiconductor or die or chip or IC) and (dummy) near lead	USPAT	2004/04/12 23:09
—	1	5198888.pn. and dummy and leads and resin and chip	USPAT	2004/04/15 15:52